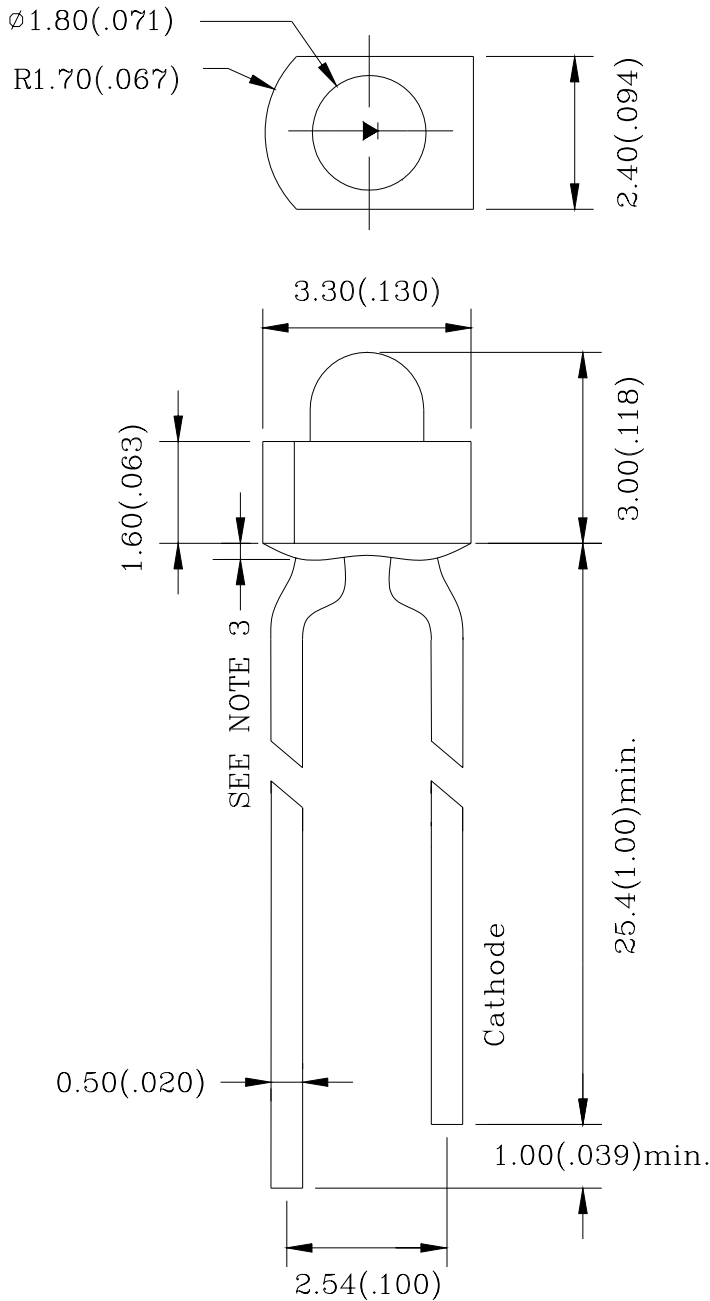


PACKAGE DIMENSIONS



- Note:**
1. All Dimensions are in millimeters.
 2. Tolerance is $\pm 0.25\text{mm}(0.010 \text{ "})$ Unless otherwise specified.
 3. Protruded resin under flange is $1.5\text{mm}(0.059 \text{ "})$ max.
 4. Lead spacing is measured where the leads emerge from the package.
 5. Specification are subject to change without notice.

FEATURES

- * SUITABLE HIGH PULSE CURRENT OPERATION
- * EXTRA HIGH RADIANT POWER AND RADIANT INTENSITY
- * HIGH RELIABILITY
- * LOW FORWARD VOLTAGE

CHIP MATERIALS

- * Dice Material : GaInN/GaN
- * Light Color : ULTRA BLUE
- * Lens Color : BLUE DIFFUSED

ABSOLUTE MAXIMUM RATING:(Ta=25°C)

SYMBOL	DESCRIPTION	ULTRA BLUE	UNIT
PAD	Power Dissipation Per Chip	80	mW
VR	Reverse Voltage Per Chip	5	V
IF	Average Forward Current Per Chip	20	mA
-	Derating Linear From 25°C Per Chip	0.4	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C±5°C For 5 Seconds			

ELECTRO-OPTICAL CHARACTERISTICS:(Ta=25°C)

SYMBOL	DESCRIPTION	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		3.2		V
IR	Reverse Current	VR = 5V			100	µA
λD	Dominant Wavelength	IF = 20mA		465		nm
Δλ	Spectral Line Half-Width	IF = 20mA		30		nm
2θ1/2	Half Intensity Angle	IF = 20mA		50		deg
IV	Luminous Intensity	IF = 20mA		550		mcd

